## MOSFET – Single, N-Channel, Small Signal, SOT-23 30 V, 0.56 A

#### **Features**

- Low Gate Voltage Threshold (V<sub>GS(TH)</sub>) to Facilitate Drive Circuit Design
- Low Gate Charge for Fast Switching
- ESD Protected Gate
- SOT-23 Package Provides Excellent Thermal Performance
- Minimum Breakdown Voltage Rating of 30 V
- NVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

## **Applications**

- Notebooks:
  - Level Shifters
  - ◆ Logic Switches
  - Low Side Load Switches
- Portable Applications

## MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parame	Symbol	Value	Unit		
Drain-to-Source Voltage	$V_{DSS}$	30	V		
Gate-to-Source Voltage			$V_{GS}$	±20	V
Continuous Drain	Steady	T <sub>A</sub> = 25°C	I <sub>D</sub>	0.5	Α
Current (Note 1)	State	T <sub>A</sub> = 85°C		0.37	
Power Dissipation (Note 1)	Steady State		P <sub>D</sub>	0.69	W
Continuous Drain	t < 10 s T <sub>A</sub> = 25°C		I <sub>D</sub>	0.56	Α
Current (Note 1)		T <sub>A</sub> = 85°C		0.40	
Power Dissipation (Note 1)	t < 5 s		P <sub>D</sub>	0.83	W
Pulsed Drain Current	t <sub>p</sub> =	: 10 μs	I <sub>DM</sub>	1.7	Α
Operating Junction and S	T <sub>J</sub> , Tstg	–55 to 150	°C		
Source Current (Body Diode)			Is	1.0	Α
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

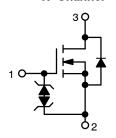


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V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> MAX	
30 V	1.0 Ω @ 4.0 V	0.56 A	
	1.5 Ω @ 2.5 V	5,557.	

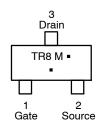
#### N-Channel



## MARKING DIAGRAM/ PIN ASSIGNMENT



SOT-23 CASE 318 STYLE 21



TR8 = Specific Device Code

M = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and overbar may vary depending upon manufacturing location.

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTR4003NT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NTR4003NT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
NVR4003NT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	180	°C/W
Junction-to-Ambient - t < 10 s (Note 1)	$R_{\theta JA}$	150	
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	300	

Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).
 Surface-mounted on FR4 board using the minimum recommended pad size.

## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified)

Symbol	Test Condition		Min	Тур	Max	Units
		•		•	•	•
V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 100 \mu\text{A}$		30			V
V <sub>(BR)DSS</sub> /T <sub>J</sub>				40		mV/°C
I <sub>DSS</sub>	$V_{GS} = 0 V, V_{DS} = 30 V$	T <sub>J</sub> = 25°C			1.0	μΑ
I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS}$	s = ±10 V			±1.0	μΑ
V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D}$	= 250 μΑ	0.8		1.4	V
V <sub>GS(TH)</sub> /T <sub>J</sub>				3.4		mV/°C
Б	$V_{GS} = 4.0 \text{ V}, I_D = 10 \text{ mA}$ $V_{GS} = 2.5 \text{ V}, I_D = 10 \text{ mA}$			1.0	1.5	
H <sub>DS(on)</sub>				1.5	2.0	Ω
9 <sub>FS</sub>	$V_{DS} = 3.0 \text{ V}, I_{D}$	) = 10 mA		0.33		S
C <sub>iss</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 5.0 \text{ V}$			21	42	pF
C <sub>oss</sub>				19.7	40	
C <sub>rss</sub>				8.1	16	
Q <sub>G(TOT)</sub>				1.15		
Q <sub>G(TH)</sub>	Voc = 5.0 V. Vpc = 24 V			0.15		7
$Q_{GS}$	$I_D = 0.$	1 A		0.32		nC
$Q_{GD}$				0.23		
)						
t <sub>d(on)</sub>				16.7		
t <sub>r</sub>	V <sub>GS</sub> = 4.5 V, V <sub>I</sub>	on = 5.0 V,		47.9		
t <sub>d(off)</sub>	$I_{D} = 0.1 \text{ A}, R_{G} = 50 \Omega$			65.1		ns -
t <sub>f</sub>				64.2		
TICS						
$V_{SD}$	$V_{GS} = 0 V$	T <sub>J</sub> = 25°C		0.65	0.7	V
	$I_S = 10 \text{ mA}$	T <sub>J</sub> = 125°C		0.45		7
t <sub>RR</sub>	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 8A/\mu s,$ $I_{S} = 10 \text{ mA}$			14		ns
	V(BR)DSS V(BR)DSS/TJ  IDSS IGSS  VGS(TH) VGS(TH)/TJ  RDS(on)  9FS  C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub> QG(TOT) QGS QGD )  t <sub>d</sub> (on) t <sub>r</sub> t <sub>d</sub> (off) t <sub>f</sub> TICS  VSD	$\begin{array}{ c c c c }\hline V_{(BR)DSS} & V_{GS} = 0 \ V, \ I_D \\ \hline V_{(BR)DSS}/T_J \\ \hline I_{DSS} & V_{GS} = 0 \ V, \\ V_{DS} = 30 \ V \\ \hline I_{GSS} & V_{DS} = 0 \ V, \ V_{GS} \\ \hline V_{GS}(TH) & V_{GS} = V_{DS}, \ I_D \\ \hline V_{GS(TH)/T_J} \\ \hline R_{DS(on)} & V_{GS} = 4.0 \ V, \ I_D \\ \hline V_{GS} = 2.5 \ V, \ I_D \\ \hline V_{GS} = 2.5 \ V, \ I_D \\ \hline V_{DS} = 3.0 \ V, \ I_D \\ \hline C_{iss} & V_{DS} = 3.0 \ V, \ I_D \\ \hline C_{rss} & V_{GS} = 5.0 \ V, \ V_{ID} \\ \hline Q_{G(TOT)} & V_{GS} = 5.0 \ V, \ V_{ID} \\ \hline Q_{GS} & V_{ID} & V_{ID} \\ \hline V_{GS} = 4.5 \ V, \ V_{ID} \\ \hline TICS & V_{GS} = 0 \ V, \ I_{ID} = 0.1 \ A, \ R_{ID} \\ \hline TICS & V_{GS} = 0 \ V, \ I_{IS} = 10 \ mA \\ \hline \end{array}$	$\begin{array}{ c c c c }\hline V_{(BR)DSS} & V_{GS} = 0 \text{ V, } I_{D} = 100 \ \mu\text{A} \\ \hline V_{(BR)DSS}/T_{J} & \\ \hline I_{DSS} & V_{GS} = 0 \text{ V, } \\ V_{DS} = 30 \text{ V} & \\ \hline I_{GSS} & V_{DS} = 0 \text{ V, } V_{GS} = \pm 10 \text{ V} \\ \hline \hline V_{GS}(TH) & V_{GS} = V_{DS}, I_{D} = 250 \ \mu\text{A} \\ \hline V_{GS}(TH)/T_{J} & \\ \hline R_{DS}(on) & V_{GS} = 4.0 \text{ V, } I_{D} = 10 \text{ mA} \\ \hline V_{GS} = 2.5 \text{ V, } I_{D} = 10 \text{ mA} \\ \hline V_{GS} = 2.5 \text{ V, } I_{D} = 10 \text{ mA} \\ \hline V_{GS} = 3.0 \text{ V, } I_{D} = 10 \text{ mA} \\ \hline \hline V_{GS} = 0 \text{ V, } I_{D} = 10 \text{ mA} \\ \hline \hline V_{GS} = 5.0 \text{ V} & \\ \hline V_{DS} = 5.0 \text{ V} \\ \hline \hline V_{GS} = 5.0 \text{ V, } V_{DS} = 24 \text{ V, } \\ \hline \hline V_{GS} = 0.1 \text{ A} & \\ \hline \hline V_{GS} = 4.5 \text{ V, } V_{DD} = 5.0 \text{ V, } \\ \hline \hline V_{GS} = 0.1 \text{ A, } R_{G} = 50 \ \Omega \\ \hline \hline TICS & \\ \hline \hline T_{J} = 125^{\circ}C \\ \hline \hline T_{J} = 125^{\circ}C \\ \hline \hline \hline \hline T_{J} = 125^{\circ}C \\ \hline \hline T_{J} = 125^{\circ}C \\ \hline \hline \hline T_{J} = 125^{\circ}C \\ \hline T_{J} = 125^{\circ}C \\ \hline \hline $	$\begin{array}{ c c c c c }\hline V_{(BR)DSS} & V_{GS} = 0 \ V, \ I_{D} = 100 \ \mu A & 30\\ \hline V_{(BR)DSS}/T_{J} & & & & & & & & & & & & & & & & & & &$	$\begin{array}{ c c c c c }\hline V_{(BR)DSS} & V_{GS} = 0 \ V, \ I_D = 100 \ \mu A & 30 \\ \hline V_{(BR)DSS}/T_J & 40 \\ \hline I_{DSS} & V_{GS} = 0 \ V, \\ V_{DS} = 30 \ V & T_J = 25^{\circ}C \\ \hline I_{GSS} & V_{DS} = 0 \ V, V_{GS} = \pm 10 \ V \\ \hline V_{GS(TH)} & V_{GS} = V_{DS}, I_D = 250 \ \mu A & 0.8 \\ \hline V_{GS(TH)}/T_J & 3.4 \\ \hline V_{GS}(TH)/T_J & 3.4 \\ \hline V_{GS} = 2.5 \ V, I_D = 10 \ mA & 1.0 \\ \hline V_{GS} = 2.5 \ V, I_D = 10 \ mA & 0.33 \\ \hline \hline C_{ISS} & V_{DS} = 3.0 \ V, I_D = 10 \ mA & 0.33 \\ \hline \hline C_{ISS} & V_{GS} = 0 \ V, f = 1.0 \ MHz, \\ \hline V_{GS} = 5.0 \ V & 19.7 \\ \hline C_{TSS} & 8.1 \\ \hline Q_{G}(TOT) & 1.15 \\ \hline Q_{GS} & Q_{GD} & 0.23 \\ \hline O_{CS} & 0.25 \\ \hline O_{CS}$	$\begin{array}{ c c c c c c }\hline V_{(BR)DSS} & V_{GS} = 0 \ V, \ I_D = 100 \ \mu A & 30 & 40 \\ \hline V_{(BR)DSS}/T_J & 40 & 40 & 40 \\ \hline I_{DSS} & V_{GS} = 0 \ V, \ V_{DS} = 30 \ V & 1.0 \\ \hline I_{GSS} & V_{DS} = 0 \ V, V_{GS} = \pm 10 \ V & \pm 1.0 \\ \hline V_{GS(TH)} & V_{GS} = V_{DS}, \ I_D = 250 \ \mu A & 0.8 & 1.4 \\ \hline V_{GS(TH)}/T_J & 3.4 & 1.0 & 1.5 \\ \hline V_{GS} = 4.0 \ V, \ I_D = 10 \ mA & 1.0 & 1.5 \\ \hline V_{GS} = 2.5 \ V, \ I_D = 10 \ mA & 1.5 & 2.0 \\ \hline Q_{FS} & V_{DS} = 3.0 \ V, \ I_D = 10 \ mA & 0.33 \\ \hline \hline C_{ISS} & V_{GS} = 2.5 \ V, \ I_D = 10 \ mA & 0.33 \\ \hline \hline C_{ISS} & V_{GS} = 0 \ V, \ f = 1.0 \ MHz, \ V_{DS} = 5.0 \ V & 19.7 & 40 \\ \hline C_{TSS} & 0.15 & 0.15 & 0.15 \\ \hline Q_{G}(TOT) & 0.15 & 0.32 & 0.23 \\ \hline Q_{GD} & 0.23 & 0.23 \\ \hline \end{array}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: pulse width  $\leq 300~\mu s$ , duty cycle  $\leq 2\%$ .

4. Switching characteristics are independent of operating junction temperatures.

## TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

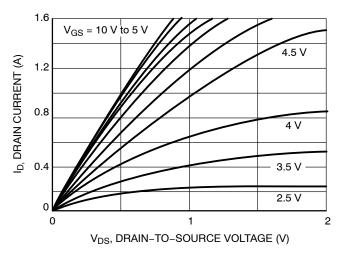


Figure 1. On-Region Characteristics

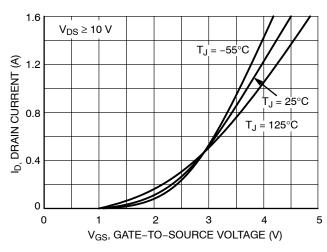


Figure 2. Transfer Characteristics

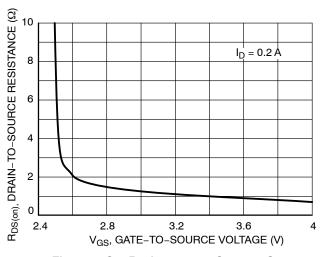


Figure 3. On-Resistance vs. Gate-to-Source Voltage

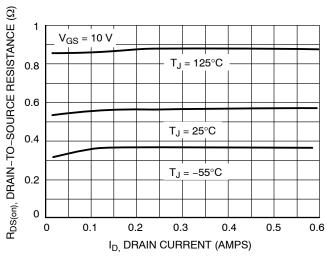


Figure 4. On–Resistance vs. Drain Current and Temperature

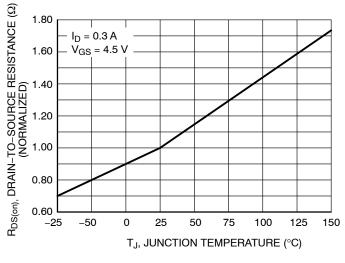


Figure 5. On–Resistance Variation with Temperature

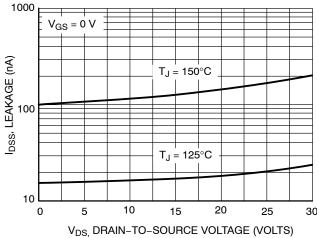


Figure 6. Drain-to-Source Leakage Current vs. Voltage

## TYPICAL PERFORMANCE CURVES ( $T_J = 25^{\circ}C$ unless otherwise noted)

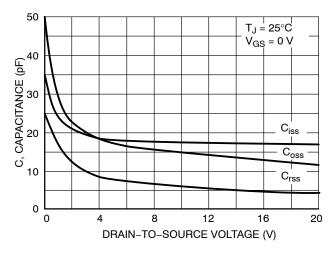


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source & Drain-to-Source Voltage vs. Total Charge

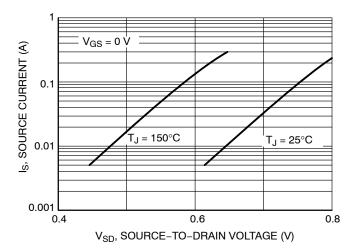


Figure 9. Diode Forward Voltage vs. Current

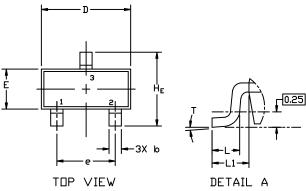




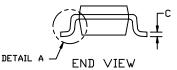
**SOT-23 (TO-236)** CASE 318 ISSUE AT

**DATE 01 MAR 2023** 









#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIM	ETERS			INCHES	
DIM	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
Ε	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0*		10°	0*		10°

# GENERIC MARKING DIAGRAM\*

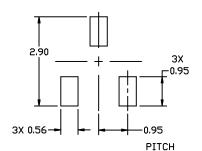


XXX = Specific Device Code

M = Date Code

■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

## **STYLES ON PAGE 2**

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## MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



## **SOT-23 (TO-236)** CASE 318 ISSUE AT

**DATE 01 MAR 2023** 

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	1	
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE	STYLE 19: I PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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